

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Appl. No. : Unassigned  
Applicant : Carapella, et al.  
Filed : 09/08/2003  
Title : METHODS OF SPLIT CAVITY WALL PLATING FOR  
AN INTEGRATED CIRCUIT PACKAGE (As Amended)

Docket No. : 42P6139CD  
Customer No. : 8791

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Which is a Divisional of:

Appl. No. : 09/665,034  
Applicant : Carapella, et al.  
Filed : 09/19/2000  
Title : METHODS FORMING AN INTEGRATED CIRCUIT  
PACKAGE WITH A SPLIT WALL (As Amended)  
TC/A.U. : 3729  
Examiner : Chang, Rick Kiltae

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Which is a Continuation of:

Appl. No. : 09/153,630  
Applicant : Carapella, et al.  
Filed : 09/15/1998  
Title : SPLIT CAVITY WALL PLATING FOR AN  
INTEGRATED CIRCUIT PACKAGE

PRELIMINARY AMENDMENT ACCOMPANYING  
35 USC 120 and 37 CFR 1.53(b)(1) DIVISIONAL APPLICATION

Mail Stop New Application  
Commissioner for Patents  
Alexandria, VA 22313

Dear Sir:

Prior to a first examination in the 35 USC 120 and 37  
CFR 1.53(b)(1) divisional application filed herewith, please  
enter the following amendments:

Title Amendments begin on page 2.  
Specification Amendments begin on page 3.  
Drawing Amendments begin on page 6.  
Claim Amendments begin on page 7.  
Remarks begin on page 15.  
Conclusion with signature is on page 21.

IN THE TITLE

Please amend the Title of the Application as follows:

"METHODS OF SPLIT CAVITY WALL PLATING FOR AN INTEGRATED CIRCUIT PACKAGE".